



# 100 CMOS

## EATU ES

MicroSIZ PACKAGE: SOT23-3

LOW DF OUT: 1mV

HIGH OUT CURRENT: 25mA

OW TEENERATURE DRIFT: 100ppm/°C max

HIGH A RACY: 2%
LOW I<sub>C</sub> LA max

## PPL

PORTA BATTERY-POWERED EQUIPMENT

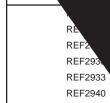
DATA JISITION SYSTEMS

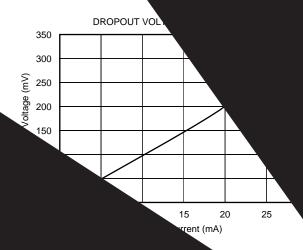
QUIPMENT

0

HELD TEST EQUIPMENT

1h tem







Please Texas

All ademarks are

'ROL JCTION DATA informa' rod cts conform to specifica tandard warranty. Production esting of all parameters. tical applications of

#### **ABSOLUTE MAXIMUM RATINGS**(1)

Supply Voltage, V+ to V	7.0V
Output Short-Circuit <sup>(2)</sup>	
Operating Temperature	
Storage Temperature	65°C to +125°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these, or any other conditions beyond those specified, is not implied. (2) Short-circuit to ground.



## ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR <sup>(1)</sup>	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
REF2912	SOT23-3	DBZ "	-40°C to +125°C	R29A "	REF2912AIDBZT REF2912AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF2920	SOT23-3	DBZ "	-40°C to +125°C	R29B "	REF2920AIDBZT REF2920AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF2925	SOT23-3	DBZ "	-40°C to +125°C	R29C "	REF2925AIDBZT REF2925AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF2930	SOT23-3	DBZ "	–40°C to +125°C	R29D "	REF2930AIDBZT REF2930AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF2933	SOT23-3	DBZ "	-40°C to +125°C	R29E "	REF2933AIDBZT REF2933AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF2940	SOT23-3	DBZ "	-40°C to +125°C	R29F "	REF2940AIDBZT REF2940AIDBZR	Tape and Reel, 250 Tape and Reel, 3000

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or see the TI web site at www.ti.com.

## **ELECTRICAL CHARACTERISTICS**

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

At  $T_A = +25$ °C,  $I_{LOAD} = 0$ mA,  $V_{IN} = 5$ V, unless otherwise noted.

				REF29xx		
PARAMETER		CONDITIONS	MIN	TYP	MAX	UNITS
		REF2912-1.25V				
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		1.225	1.25	1.275 2	V %
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		14 42		μV <sub>PP</sub> μVrms
LINE REGULATION		$1.8V \le V_{IN} \le 5.5V$		60	190	μV/V
	•	REF2920	-			
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		2.007	2.048	2.089	V %
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		23 65		μV <sub>PP</sub> μVrms
LINE REGULATION		$V_{REF}$ + 50mV $\leq V_{IN} \leq 5.5V$		110	290	μV/V
		REF2925				
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		2.450	2.50	2.550 2	V %
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		28 80		μV <sub>PP</sub> μVrms
LINE REGULATION		$V_{REF}$ + 50mV $\leq V_{IN} \leq 5.5V$		120	325	μV/V

## **ELECTRICAL CHARACTERISTICS (Cont.)**

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

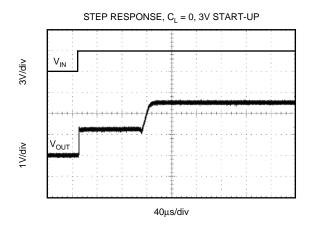
At  $T_A$  = +25°C,  $I_{LOAD}$  = 0mA,  $V_{IN}$  = 5V, unless otherwise noted.

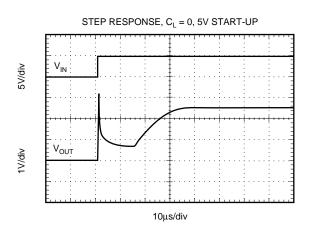
			REF29xx			
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
	REF2930					
OUTPUT VOLTAGE V <sub>OUT</sub>		2.940	3.0	3.06 2	V %	
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		33 94		μV <sub>PP</sub> μVrms	
LINE REGULATION	$V_{REF}$ + 50mV $\leq V_{IN} \leq 5.5V$		120	375	μV/V	
	REF2933	•				
OUTPUT VOLTAGE V <sub>OUT</sub>		3.234	3.30	3.366 2	V %	
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		36 105		μV <sub>PP</sub> μVrms	
LINE REGULATION	$V_{REF}$ + $50mV \le V_{IN} \le 5.5V$		130	400	μV/V	
	REF2940					
OUTPUT VOLTAGE V <sub>OUT</sub>		4.014	4.096	4.178 2	V %	
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		45 128		μV <sub>PP</sub> μVrms	
LINE REGULATION	$V_{REF} + 50 \text{mV} \le V_{IN} \le 5.5 \text{V}$		160	410	μV/V	
REF2912, REF	F2920, REF2925, REF2930, REF	2933, REF294	0			
OUTPUT VOLTAGE TEMP DRIFT <sup>(2)</sup> dV <sub>OUT</sub> /dT	-40°C ≤ T <sub>A</sub> ≤ +125°C		35	100	ppm/°C	
OUTPUT CURRENT I <sub>LOAD</sub>	*			25	mA	
LONG-TERM STABILITY	0-1000 <sub>H</sub> 1000-2000 <sub>H</sub>		24 15		ppm ppm	
LOAD REGULATION <sup>(3)</sup> dV <sub>OUT</sub> /dl <sub>LOAD</sub>	$0mA < I_{LOAD} < 25mA,$ $V_{IN} = V_{REF} + 500mV^{(1)}$		3	100	μV/mA	
THERMAL HYSTERESIS(4) dT			25	100	ppm	
DROPOUT VOLTAGE V <sub>IN</sub> – V <sub>OUT</sub>			1	50	mV	
SHORT-CIRCUIT CURRENT I <sub>SC</sub>			45		mA	
TURN-ON SETTLING TIME	to 0.1% at $V_{IN} = 5V$ with $C_L = 0$		120		μs	
POWER SUPPLY           Voltage         V <sub>S</sub> Over Temperature         U <sub>Q</sub> Quiescent Current         I <sub>Q</sub> Over Temperature         I <sub>Q</sub>	$I_{L} = 0$ $-40^{\circ}C \le T_{A} \le +125^{\circ}C$ $-40^{\circ}C \le T_{A} \le +125^{\circ}C$	V <sub>REF</sub> + 0.001 <sup>(5)</sup> V <sub>REF</sub> + 0.05	42	5.5 <b>5.5</b> 50 <b>59</b>	V <b>V</b> μΑ μ <b>A</b>	
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance		-40 -40 -65		+125 +125 +150	ဝိဝိဝိ	
SOT23-3 Surface-Mount $\theta_{JC}$			110 336		°C/W	

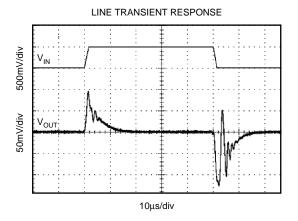
NOTES: (1) Minimum supply voltage for REF2912 is 1.8V. (2) Box Method used to determine over temperature drift. (3) Typical value of load regulation reflects measurements using a force and sense contacts, see text "Load Regulation". (4) Thermal hysteresis procedure is explained in more detail in Applications Information section of data sheet. (5) For  $I_L > 0$ , see Typical Characteristic curves.

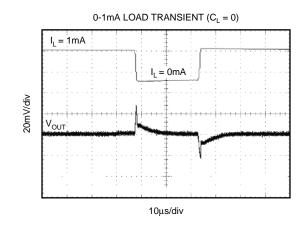
## **TYPICAL CHARACTERISTICS (Cont.)**

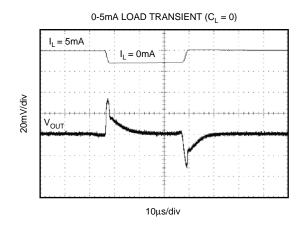
At  $T_A = +25^{\circ}C$ ,  $V_{IN} = +5V$  power supply, REF2925 is used for typical characteristics, unless otherwise noted.

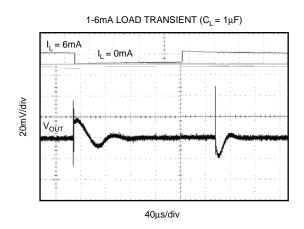














### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
REF2912AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2912AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2912AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2912AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2920AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2920AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2920AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2920AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2925AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2925AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2925AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2925AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2930AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2930AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2930AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2930AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2933AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2933AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2933AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2933AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2940AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2940AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2940AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF2940AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $<sup>^{(1)}</sup>$  The marketing status values are defined as follows:



#### PACKAGE OPTION ADDENDUM

8-Feb-2008

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

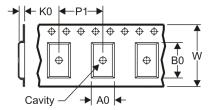
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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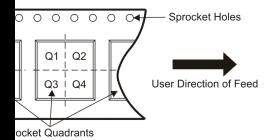
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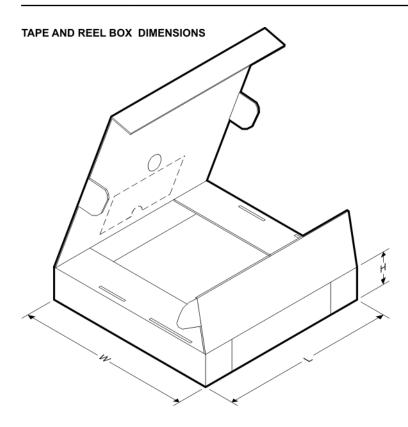
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TS FOR PIN 1 ORIENTATION IN TAPE



SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	



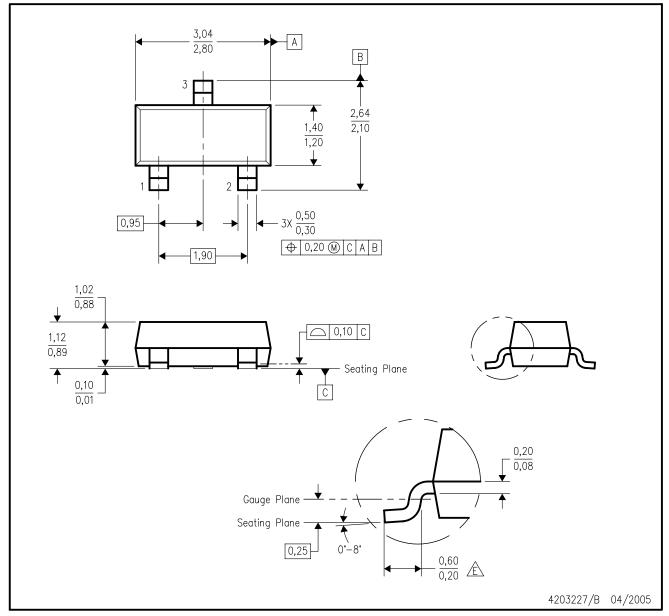


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REF2912AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2912AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
REF2920AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2920AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
REF2925AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2925AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
REF2930AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2930AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
REF2933AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2933AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
REF2940AIDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
REF2940AIDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0

## DBZ (R-PDSO-G3)

## PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



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